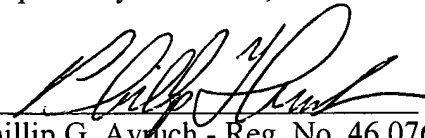


REMARKS

Claims 2-4 are cancelled. Claims 5-32 have been added. Please enter the Preliminary Amendment prior to calculating the filing fee. Examination of the amended application is respectfully requested.

Respectfully submitted,

December 26, 2001
Date


Phillip G. Avrich - Reg. No. 46,076
RABIN & BERDO, P.C.
Telephone: 202-659-1915
Telefax: 202-659-1898
CUSTOMER NO. 23995

SMR:tlc

RECEIVED

A

MARKED VERSION OF AMENDED CLAIM

1. (Amended) A method of forming a resist pattern on a semiconductor substrate, comprising [the steps of]:
 - forming a resist film on the semiconductor substrate;
 - supplying a developing solution [onto] on the resist film to remove the resist film,
 - wherein a portion of the resist film remains on the semiconductor substrate; and
 - [submerging the substrate and the resist film formed thereon in a rinsing liquid kept in a rinsing tank; and
 - applying ultrasonic vibration to the rinsing liquid to rinse the developing solution from the resist film submerged in the rinsing liquid]
 - rinsing the developing solution from the portion of the resist film by a rinsing liquid to which ultrasonic vibration is applied.

11/03/2011 10:00 AM

A